

2A, 20V - 150V Schottky Barrier Surface Mount Rectifier

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for over-voltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.093g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	2	A
V_{RRM}	20 - 150	V
I_{FSM}	50	A
$T_{J\ MAX}$	125, 150	°C
Package	DO-214AA (SMB)	
Configuration	Single die	



DO-214AA (SMB)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)											
PARAMETER	SYMBOL	SS 22	SS 23	SS 24	SS 25	SS 26	SS 29	SS 210	SS 215	UNIT	
Marking code on the device		SS 22	SS 23	SS 24	SS 25	SS 26	SS 29	SS 210	SS 215		
Repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	90	100	150	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	14	21	28	35	42	63	70	105	V	
Forward current	I_F	2								A	
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50								A	
Critical rate of rise of off-state voltage	dV/dt	10,000								V/ μs	
Junction temperature	T_J	- 55 to +125			- 55 to +150					°C	
Storage temperature	T_{STG}	- 55 to +150									°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	24	$^{\circ}C/W$
Junction-to-ambient thermal resistance	$R_{\theta JA}$	70	$^{\circ}C/W$

ELECTRICAL SPECIFICATIONS (TA = 25°C unless otherwise noted)									
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT			
Forward voltage ⁽¹⁾	SS22 SS23 SS24	$I_F = 2A, T_J = 25^{\circ}C$	V_F	-	0.50	V			
	SS25 SS26			-	0.70	V			
	SS29 SS210			-	0.85	V			
	SS215			-	0.95	V			
	Forward voltage ⁽¹⁾			SS22 SS23 SS24	$I_F = 2A, T_J = 100^{\circ}C$	V_F	-	0.40	V
				SS25 SS26			-	0.65	V
SS29 SS210		-	0.70	V					
SS215		-	0.80	V					
Reverse current @ rated $V_R^{(2)}$		SS22 SS23 SS24	$T_J = 25^{\circ}C$	I_R			-	400	μA
	SS25 SS26	-			100	μA			
	SS29 SS210 SS215	-			-	-			
	Reverse current @ rated $V_R^{(2)}$	SS22 SS23 SS24			$T_J = 100^{\circ}C$	I_R	-	10	mA
		SS25 SS26					-	5	mA
		SS29 SS210 SS215					-	-	mA

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Reverse current @ rated $V_R^{(2)}$	SS22 SS23 SS24	$T_J = 125^\circ\text{C}$	I_R	-	-	mA
	SS25 SS26			-	-	mA
	SS29 SS210 SS215			-	5	mA

Notes:

1. Pulse test with $PW = 0.3\text{ms}$
2. Pulse test with $PW = 30\text{ms}$

ORDERING INFORMATION

ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
SS2x	DO-214AA (SMB)	3,000 / Tape & Reel

Notes:

1. "x" defines voltage from 20V(SS22) to 150V(SS215)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

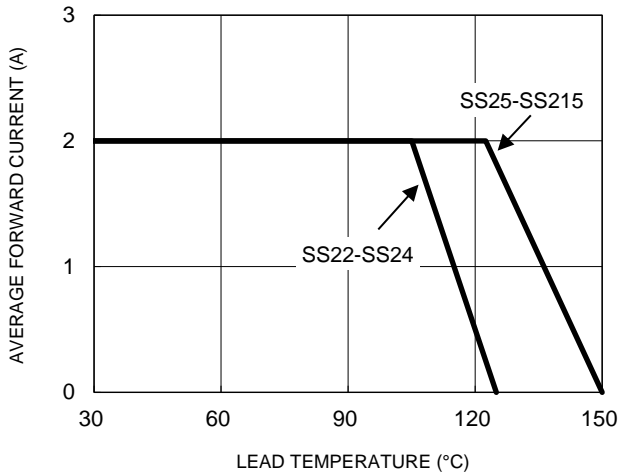


Fig.2 Typical Junction Capacitance

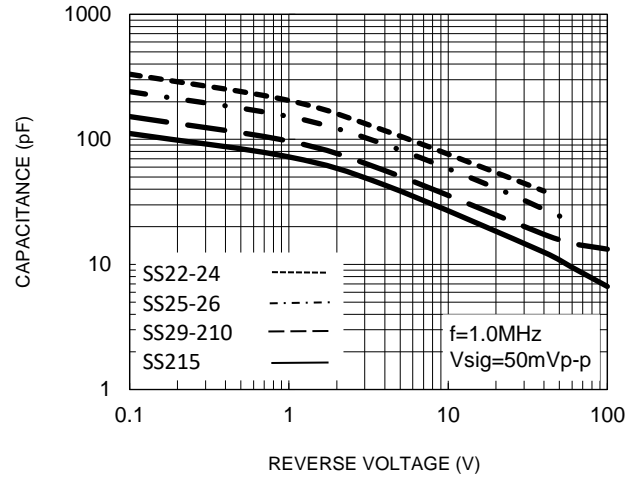


Fig.3 Typical Reverse Characteristics

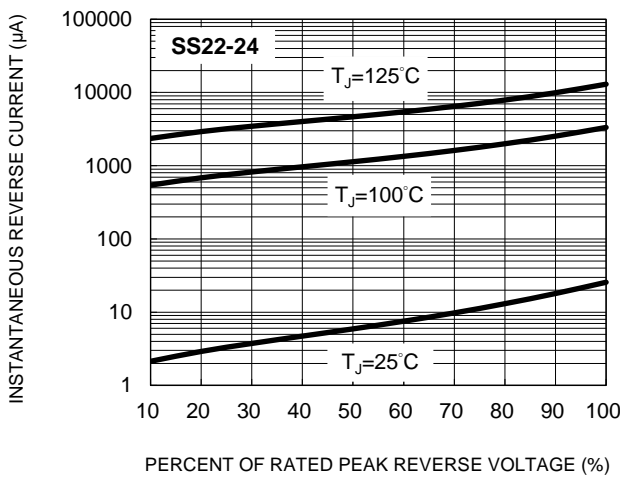


Fig.4 Typical Forward Characteristics

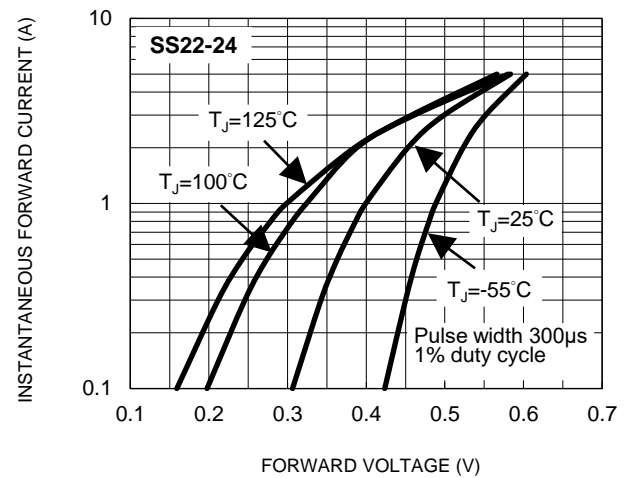


Fig.5 Typical Reverse Characteristics

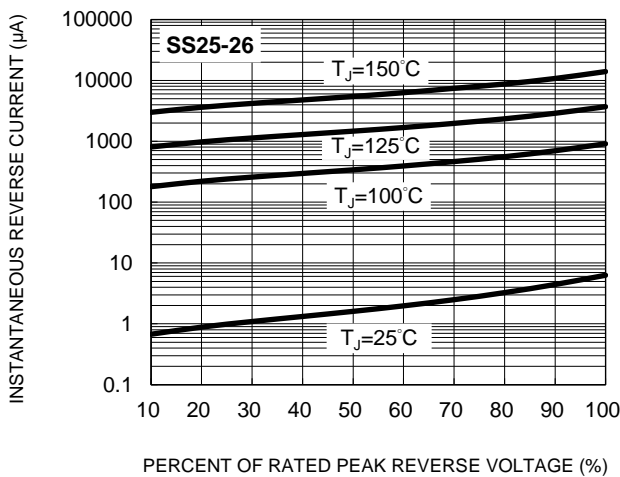
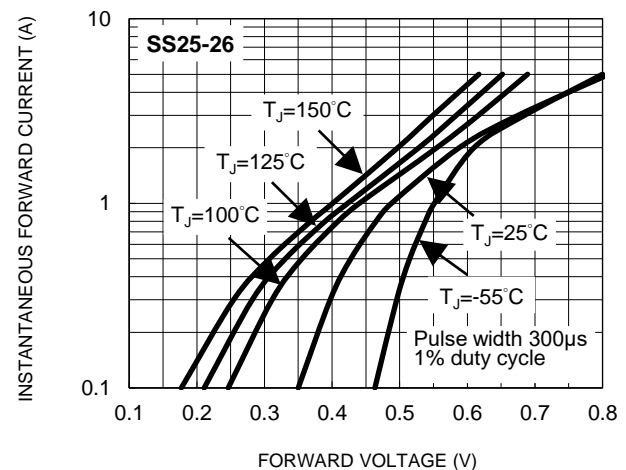


Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.7 Typical Reverse Characteristics

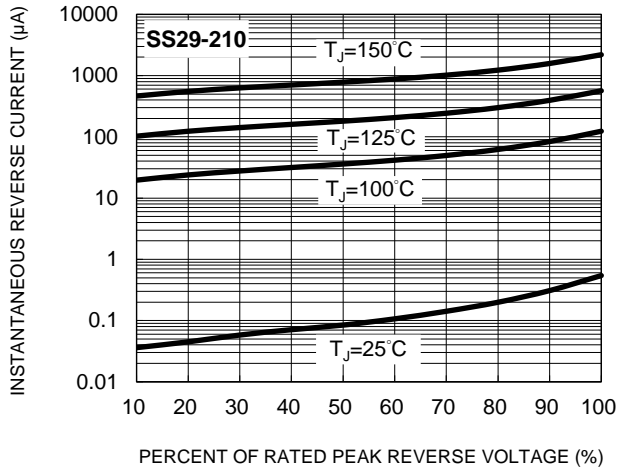


Fig.8 Typical Forward Characteristics

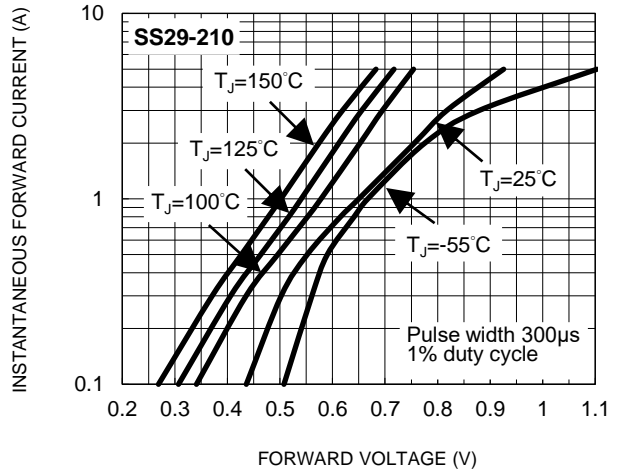


Fig.9 Typical Reverse Characteristics

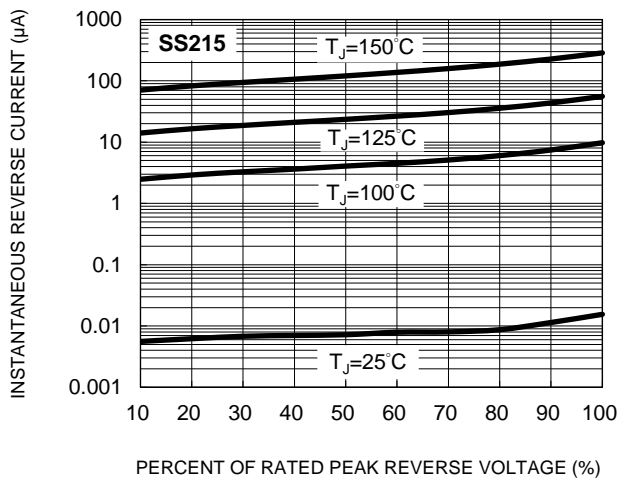


Fig.10 Typical Forward Characteristics

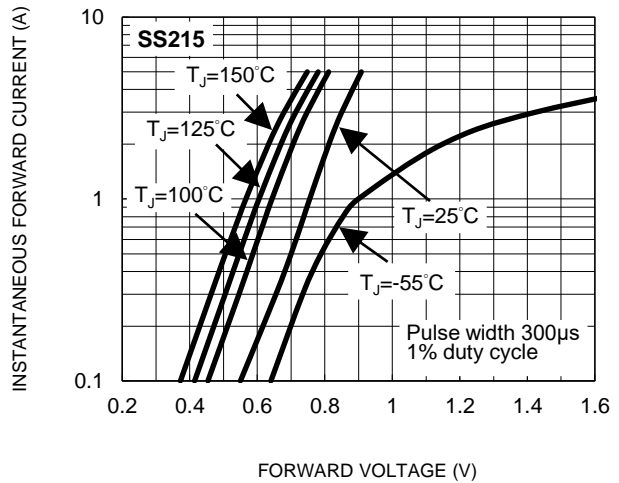
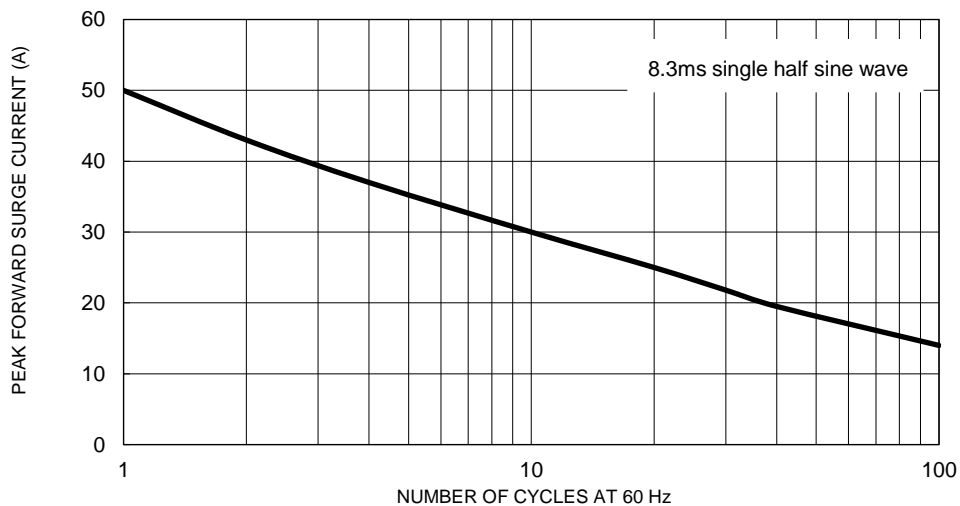
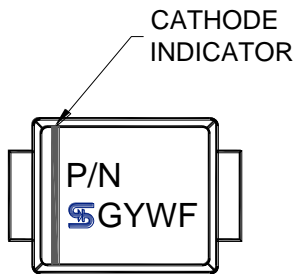
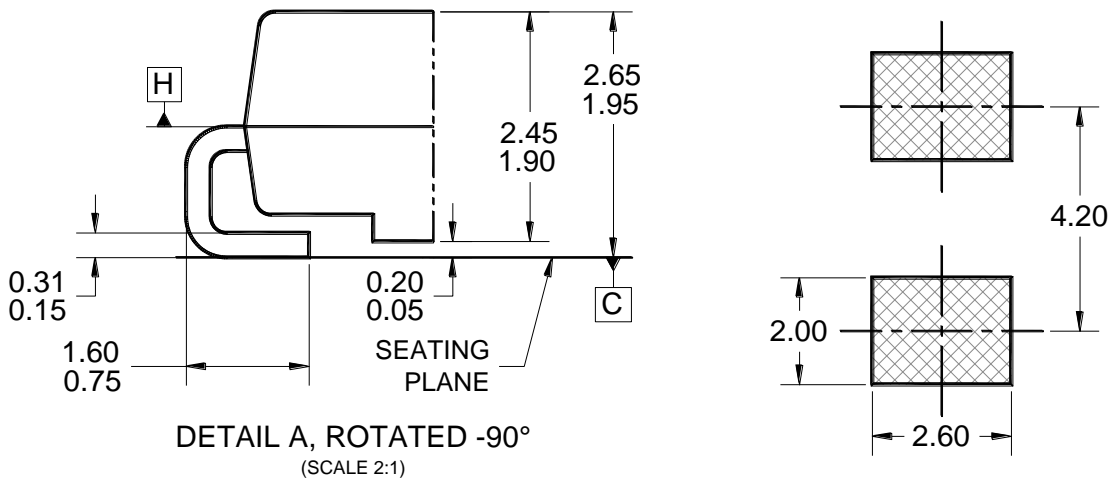
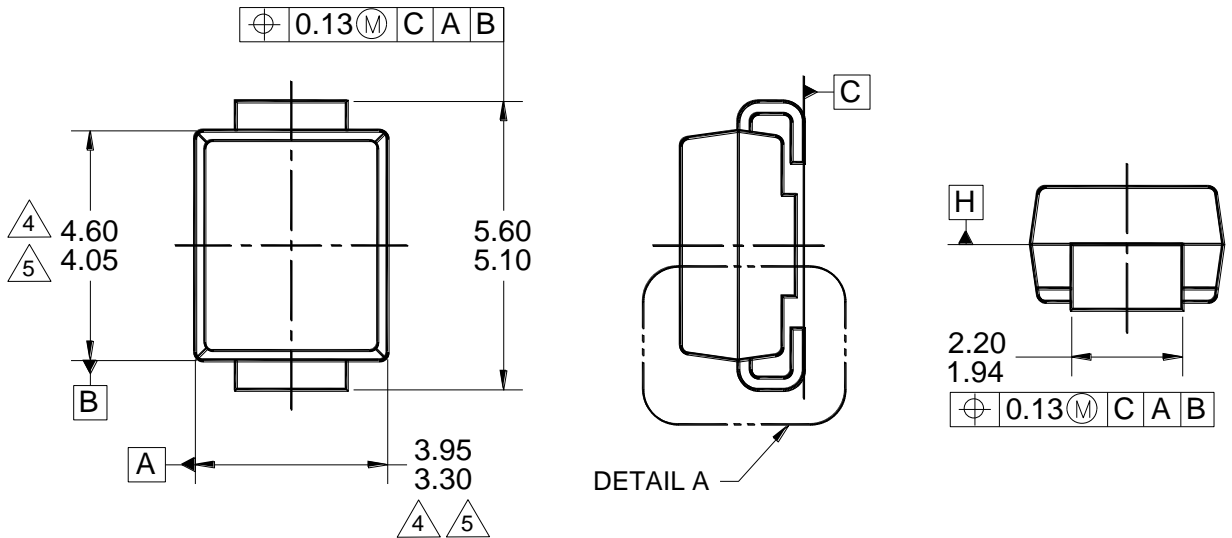


Fig.11 Maximum Non-Repetitive Forward Surge Current



PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



MARKING DIAGRAM

P/N = MARKING CODE
G = GREEN COMPOUND
YW = DATE CODE
F = FACTORY CODE

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AA, ISSUE D.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
5. MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
6. DWG NO. REF: HQ2SD07-DO214SMB-035 REV A.

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